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| TITLE OF INVENTION: | Perforated Plate for Wafer Chuck |
| APPLICANT: ADDRESS: | ✓ Systems on Silicon Manufacturing Co. Pte. Ltd. 70, Pasir Ris Industrial Drive 1 Singapore 519527 Singapore |
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| COUNTRY OF PERMANENT RESIDENCY: NATIONALITY: | SINGAPORE MALAYSIAN (SINGAPORE PERMANENT RESIDENCE) |
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INVENTOR 5:
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COUNTRY OF PERMANENT
RESIDENCY:
NATIONALITY:

SINGAPORE
CHINESE (SINGAPORE PERMANENT
RESIDENCE)

PRIORITY TO BE CLAIMED:-

None

INTERNATIONAL APPLICATION NO.

PCT/SG03/00170

INTERNATIONAL FILING DATE:

14 JULY 2003